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DOCKET NO. END920020007US1

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Choi *et al.*

Examiner: Zimmerman, John J.

Serial No.: 10/078,020

Art Unit: 1775

Filed: 2/15/2002

For: **LEAD-FREE TIN-SILVER-COPPER ALLOY SOLDER COMPOSITION**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

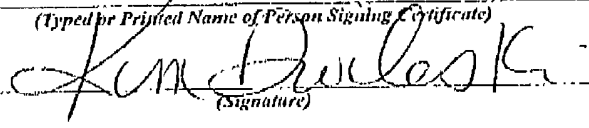
AMENDMENT

Sir:

In response to the Final Office Action mailed February 11, 2004, please amend the above-identified application as follows:

10/078,020

1

<b>CERTIFICATE OF TRANSMISSION BY FACSIMILE (37 CFR 1.8)</b>			Docket No. END920020007US1
Applicant(s): Choi et al.			
Serial No. 10/078,020	Filing Date 2/15/2002	Examiner Zimmerman, John J.	Group Art Unit 1775
Invention: LEAD-FREE TIN-SILVER-COPPER ALLOY SOLDER COMPOSITION			
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Kim Dwileski (Typed or Printed Name of Person Signing Certificate)  (Signature)			
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